

/ Descriptions

WO-223FAC

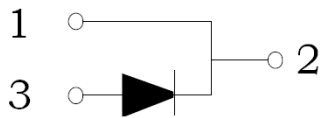
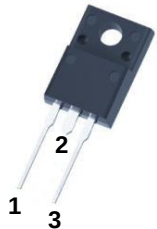
Ultrafast Recovery Diode in a TO-220FAC Plastic Package.

/ Features τ H_f

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode

/ Equivalent Circuit**/ Pinning**

PIN1 2 Cathode

PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions

/ Absolute Maximum Ratings(Ta=25)

Parameter	N Symbol	Rating	H Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
RMS Voltage	V_{RMS}	420	V
DC Blocking Voltage	V_{DC}	600	V
Forward Current	I_F	1 × 8	A
Peak forward surge current	I_{FSM}	100	A
Typical Thermal Resistance Junction to Case	$R_{\theta Jc}$	4	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	N Symbol	Test Conditions	Min	ε Typ	Max	H Unit
Reverse Voltage	V_R	$I_R=1mA$	600			V
Forward Voltage	V_F	$I_F=1.0A$ $T_C=25$		0.91	1.1	V
		$I_F=1.0A$ $T_C=125$		0.69	0.8	
		$I_F=8A$ $T_C=25$		1.28	1.5	
		$I_F=8A$ $T_C=125$		1.13	1.35	
Instantaneous Reverse Current	I_R Note 1	$V_R=600V$ $T_a=25$			10	μA
		$V_R=600V$ $T_a=125$			500	
Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_R=1.0A$ $I_{RR}=0.25A$			50	ns

2Notes

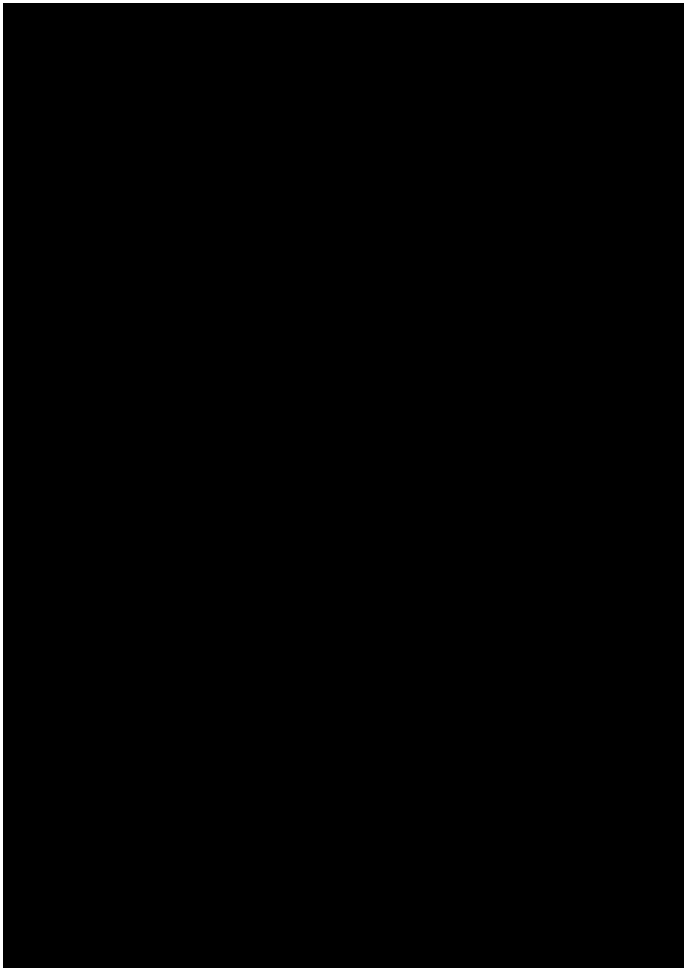
1. Short duration pulse test used to minimize self-heating effect.
2. Unless otherwise noted, values for the parameters of a single chip

/ Electrical Characteristic Curve

/ PackageDimensions



/ Marking Instructions



BR	И		
MXRF863		N	
****		N	N

Note:

BR:	Company Code
MXRF863	Product Type.
****:	Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm ³)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-220/F/AC/FAC	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

/ TUBE

Package Type	Units					Dimension (unit mm ³)		
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
TO-220/F/AC/FAC	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

/ Notices